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Name and Address of Receiving Party:
SUMITOMO METAL (SMI) ELECTRONICS DEVICES ,INC.
2701-1, Aza-Iwakura, Higashibun, Ohmine-cho,
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Nature of Conveyance:
 Assignment Security Agreement Merger License
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Execution Date of Document: January 7, 1998

If this document is being filed together with a new application, the execution date of the application is:

Patent Application Numbers: Patent Numbers:
08/980 179 ---

Total Number of Applications and Patents Involved: 1. An enclosed check includes the recording fee of \$40.00. The Commissioner is hereby authorized to credit any overpayment, or to charge any additional recording fee required by this paper, to Deposit Account No. 06-1382.

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To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.

Respectfully submitted,


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120.9510

A S S I G N M E N T

**United States (Sole or Joint)
(Excluding Foreign Rights)**

WHEREAS, I/We, Masashi FUKAYA,

residing at Kayamachi 100, Kuwana-shi, Mie, Japan

have invented certain new and useful improvements in THICK-FILM PASTE AND CERAMIC CIRCUIT SUBSTRATE USING THE SAME for which an application for United States Letters Patent was filed on November 26, 1997 and received Serial No. 08/980 179.

WHEREAS, SUMITOMO METAL (SMT) ELECTRONICS DEVICES, INC.

having a place of business at 2701-1, Aza-Iwakura, Higashibun, Omimine-cho, Mine-shi, Yamaguchi, Japan

hereinafter called the "Assignee", is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefor, in the United States and its territorial possessions.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) and other valuable considerations, the receipt whereof is hereby acknowledged, I/we have sold, assigned and transferred, and by these presents do sell, assign, transfer and confirm in and to said Assignee my/our full and exclusive right to the said invention in the United States and its territorial possessions and my/our entire right, title and interest in and to said application and any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in and to any and all divisions, reissues, continuations and extensions thereof.

I/We hereby authorize and request the Patent Office Officials in the United States to issue any and all of said Letters Patent, when granted, to said Assignee for the sole use and behoof of the said Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/we have hereunto set my/our hand(s).

Witnessed by:

Inventor(s):

Date:

Takeshi Okada
Takeshi OKADA

Masashi Fukaya January 7, 1998
Masashi FUKAYA

Yoichi Matsuda
Yoichi MATSUDA